AMENDMENTS TO THE SPECIFICATION:

Please insert the following heading and paragraph beginning on page 1, line 3:

--CROSS REFERENCE TO RELATED APPLICATIONS

This application is a division of co-pending Application No. **09/788,596**, filed on **February 21, 2001**, the entire contents of which are hereby incorporated by reference.--

Please replace the paragraph beginning at page 1, line 22, and ending on page 2, line 16 with the following rewritten paragraph:

----With reference to Fig. [[6]] 7, in such a conventional semiconductor device, a semiconductor chip 21 and a wiring substrate 25 are connected to each other by welded solder balls 26 of the semiconductor chip 21. Further, resin 29 is injected into the gap between the semiconductor chip 21 and the wiring substrate 25 so as to cover the solder balls 26. The resin 29 is injected for the purpose of alleviating the thermal stress caused by the difference in the coefficient of thermal expansion between the semiconductor chip 21 and the wiring substrate 25. The semiconductor chip 21 and the wiring substrate 25 repeat expansion and contraction by heat generated by operations (on/off operation) of the device. However, the coefficient of thermal expansion of the semiconductor chip 21 is about 3.5 ppm whereas the coefficient of thermal expansion of the wiring substrate 25 is about 16 ppm in case of a printed board and about 8 ppm in case of an alumina substrate. Due to this

difference in the coefficient of thermal expansion between the semiconductor chip 21 and the wiring substrate 25, the solder balls 26 are alternately subject to compressive stress and tensile stress. As a result, the solder balls 26 are broken at an early stage due to thermal fatigue, which causes electric disconnection, resulting in a signal transmission stop or a power supply stop.----